

## **Technical Data Sheet**

# FeedBond<sup>®</sup> FP-1725-E9

## Low temperature cure Conductive Adhesive

#### Introduction:

FeedBond<sup>®</sup>FP-1725-E9 is an electrically conductive adhesive. It is designed for low temperature curing in oven.

#### **Characteristics:**

- Low cure temperature
- One component
- Good adhesion strength

UNCURED PROPERTIES		TEST DESCRIPTION	TEST METHOD
Appearance	Silver		
Viscosity @ 25°C	11000 cps	Brookfield DV-III/CP-51 @ 5rpm	FT-P006
Thixotropic Index	4.0	Brookfield DV-III/CP-51	FT-P008
@ 25°C		Visc. @ 0.5rpm/Visc. @ 5rpm	
Grind	< 25µm	Grind meter	FT-P026
Work Life @ 25°C	24 hrs	25% increase in visc. @ 5rpm	FT-P024
Shelf Life@ -40°C	6 months		FT-P018
CURE CONDITION		TEST DESCRIPTION	TEST METHOD
Standard Cure Condition in oven		120min @80°C	
		60min @100°C	
		10 min @120℃	
Standard Cure Condition on hotplate		75sec @175°C	
Die Shear Strength @ 2	$5^{\circ}C > 3 \text{ kg/die}$	45mil × $45$ mil Si die on Ag LF	FT-M012
		Cure 60min in oven @100 (	
Die Shear Strength @ 1	$50^{\circ}$ C >1 kg/die	45mil × $45$ mil Si die on Ag LF	FT-M012

Note: This table is only the test data of Feedpool laboratory, customers still need to do a complete verification test for the product before putting it into production.

## Feedpool Technology Co., Ltd.

Website: www.feedpool.com

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PHYSIOCHEMICAL POST CURE	PROPERTIES-	TEST DESCRIPTION	TEST METHOD
Glass Transition Temperature (Tg) 79°C		DMA 3 Point Bending Mode	FT-M014
Coefficient of Thermal Expansion			
Below Tg(a1)	34ppm/°C	TMA Expansion Mode	FT-M016
Above $Tg(\alpha 2)$	82 ppm/°C		
Storage Modulus @25°C @150°C @250°C	2599MPa 105MPa 215MPa	Dynamic Mechanical Thermal Analysis using <1.6mm thick specimen	FT-M019A
THERMAL ELECTRICAL PROPERTIES- POST CURE		TEST DESCRIPTION	TEST METHOD
Volume resistivity	$<0.0005\Omega\cdot cm$	Cure 60min in oven @100°C 4-point probe	FT-P017
Thermal conductivity	1.86 W/mK	Hot Disk	FT-P022

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### Instruction

This product is easy to hindered, resulting inhibit the cure. Avoid the following materials: ①Containing Amin type, Thiol type, acid anhydride. ② Alcohol, Ketone, Polar solvent (DME, NMP). ③The sulfur-containing surface treatment agent.

### Thawing

Place the container to stand vertically for 30min ~90min.**DO NOT** open the container before adhesive reaches ambient temperature to prevent the moisture condensation. Any moisture that collects on the thawed container should be removed prior to use. Adhesives that appear to have separated should not be used.

### Storage

Adhesive should be stored @  $-40^{\circ}$ C. The shelf life of the material is only valid when the material has been stored at the correct storage condition.

### Availability

FeedBond adhesives are packaged in syringes or pots per customer specification. For the details, please contact our Customer Service or sales department.